AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

- 1-4. (canceled)
- 5. (currently amended) An apparatus comprising:

an integrated circuit (IC) die;

a stack of at least three metal layers on a back surface of the IC die, said three metal layers including a first layer formed of a first material, a second layer formed of a second material different from the first material and a third layer formed of a third material different from the first and second materials;

a heat spreader conductively coupled to the stack of metal layers; and

a bias signal source coupled to the heat spreader to supply a bias signal to the IC die via the stack of metal layers.

6. (original) The apparatus of claim 5, further comprising:

a wire coupled to the heat spreader to provide the bias signal from the signal source.

7. (original) The apparatus of claim 5, further comprising:

a package substrate on which the IC die is mounted, the package substrate including a conductive path to provide the bias signal to the heat spreader.

8. (original) The apparatus of claim 5, wherein the IC die includes a microprocessor.
9-13. (canceled)
14. (previously presented) An article of manufacture, comprising:
a substrate;
an integrated circuit (IC) die mounted on the substrate;
a metal layer on a back surface of the IC die;
a heat spreader electrically coupled to the metal layer;
an electrically conductive connection to couple the heat spreader to a device external to the IC die; and
a layer of solder between the metal layer and the heat spreader.
15-19. (canceled)
20. (previously presented) An article of manufacture, comprising:
a substrate;
an integrated circuit (IC) die mounted on the substrate;
a metal layer on a back surface of the IC die;
a heat spreader electrically coupled to the metal layer;

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means for providing a signal path between the heat spreader and a device external to the IC die; and

a layer of solder between the metal layer and the heat spreader.

21-24. (canceled)

25. (previously presented) A system comprising:

a die comprising a microprocessor; and

a chipset in communication with the microprocessor;

wherein:

the die has a metal layer on a back surface of the die; and

the die is mounted in a package that includes:

a substrate on which the die is mounted;

a heat spreader electrically coupled to the metal layer;

an electrically conductive connection to couple the heat spreader to a device external to the die; and

a layer of solder between the metal layer and the heat spreader.

26. (previously presented) The article of manufacture of claim 14, wherein the electrically conductive connection passes through the substrate.

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27. (previously presented) The article of manufacture of claim 14, wherein the electrically conductive connection includes a wire that is not part of the substrate.
28. (previously presented) The article of manufacture of claim 14, wherein the IC die includes a microprocessor.
29. (previously presented) The article of manufacture of claim 14, wherein the IC die is mounted in flip-chip fashion on the substrate.
30. (previously presented) The article of manufacture of claim 20, wherein the means for providing a signal path includes a wire coupled to the heat spreader.
31. (previously presented) The article of manufacture of claim 20, wherein the means for providing a signal path includes a conductive path that passes through the substrate.
32. (previously presented) The article of manufacture of claim 20, wherein the IC die includes a microprocessor.
33. (previously presented) The article of manufacture of claim 20, wherein the IC die is mounted in flip-chip fashion on the substrate.

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- 34. (previously presented) The system of claim 25, wherein the electrically conductive connection passes through the substrate.
- 35. (previously presented) The system of claim 25, wherein the electrically conductive connection includes a wire that is not part of the substrate.
- 36. (previously presented) The system of claim 25, wherein the die is mounted in flip-chip fashion on the substrate.